

General Description

The BSC070N10NS3G use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

General Features

V_{DS} =100V I_D =75A

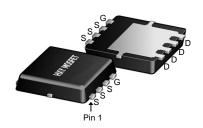
 $R_{DS(ON)}$ < 9.2m Ω @ V_{GS} =10V

Applications

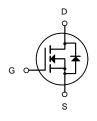
Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications



DFN5X6-8L



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
BSC070N10NS3G	DFN5X6-8L	75N10 XXX YYYYY	5000

Absolute Maximum Ratings at T_j=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	VDS	100	V
Gate source voltage	VGS	±20	V
Continuous drain current ¹⁾	ID	75	Α
Pulsed drain current ²⁾	ID, pulse	300	А
Power dissipation ³⁾	P _D	97	W
Single pulsed avalanche energy ⁵⁾	EAS	90	mJ
Operation and storage temperature	Tstg, Tj	-55 to 150	°C
Thermal resistance, junction-case	RθJC	1.3	°C/W

N-SGT Enhancement Mode MOSFET

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic		•		•	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Charac	cteristics					
V _{GS(th)}	V _{GS(th)} Gate Threshold Voltage V _{DS} =V _{GS} , I _D =250μA		1.0	1.6	2.5	V
П	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =20A -		7.3	9.2	mΩ
$R_{DS(on)}$	note3	V _{GS} =4.5V, I _D =8A -		9	13.5	mΩ
Dynamic (Characteristics					
C _{iss}	Input Capacitance		-	2046	-	pF
Coss	Output Capacitance	V _{DS} =50V, V _{GS} =0V,	-	865	-	pF
Crss	Reverse Transfer Capacitance	f=1.0MHz	-	25	-	pF
Qg	Total Gate Charge	\/ -E0\/ -20A	-	39.4	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =50V, I _D =30A, V _{GS} =10V	-	5.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	VGS-10V	-	9.8	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	20	-	ns
t r	Turn-on Rise Time	V _{DD} =50V, I _D =25A,	-	5.2	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=6\Omega$, $V_{GS}=10V$	-	49	-	ns
t _f	Turn-off Fall Time		-	12	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
1.	Maximum Continuous Drain to Source Diode Forward Current				75	Α
I _S				-	75	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	300	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1	٧
t _{rr}	Body Diode Reverse Recovery Time	T -25°C	-	49	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge	T _J =25℃, I _F =12A,dI/dt=100A/μs	-	85	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition: TJ=25 $^{\circ}\text{C}$, VDD=50V, VG=10V, RG=25 Ω , L=0.5mH, IAS=19A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

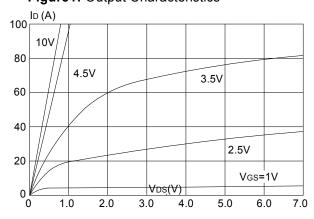


Figure 3:On-resistance vs. Drain Current

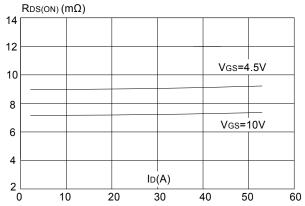


Figure 5: Gate Charge Characteristics

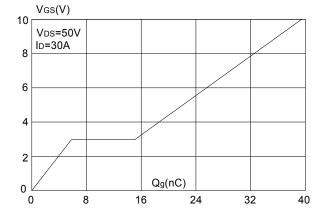


Figure 2: Typical Transfer Characteristics

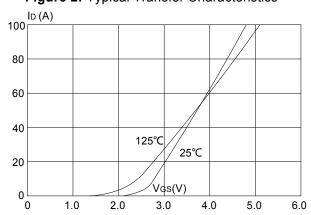


Figure 4: Body Diode Characteristics

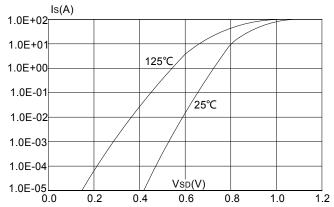


Figure 6: Capacitance Characteristics

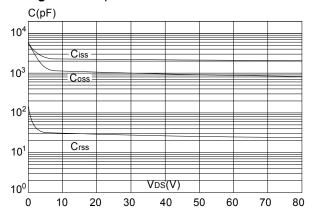




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

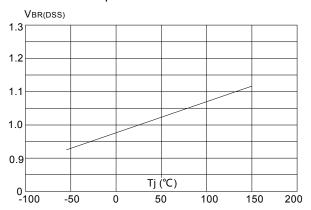


Figure 9: Maximum Safe Operating Area

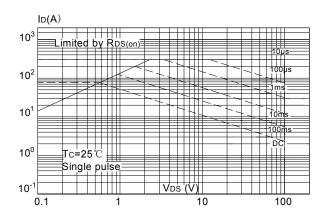


Figure.11: Maximum Effective
Transient Thermal Impedance, Junction-to-Case

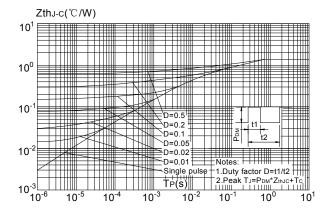


Figure 8: Normalized on Resistance vs. Junction Temperature

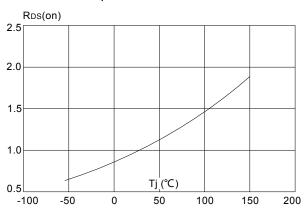
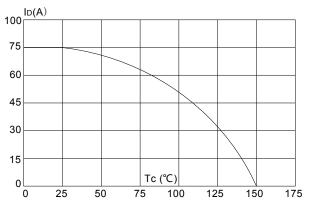


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

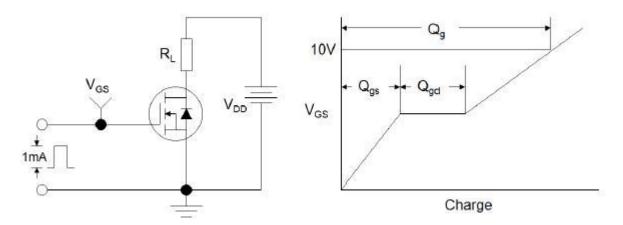


Figure1:Gate Charge Test Circuit & Waveform

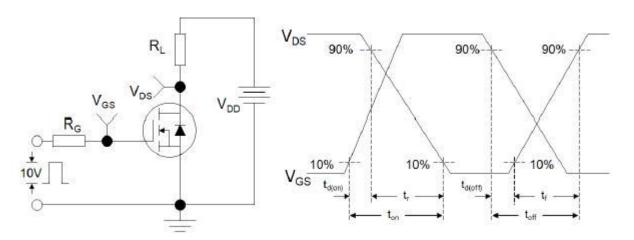


Figure 2: Resistive Switching Test Circuit & Waveforms

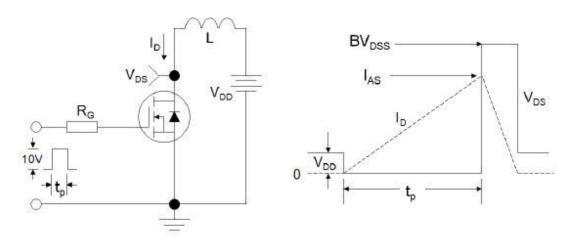
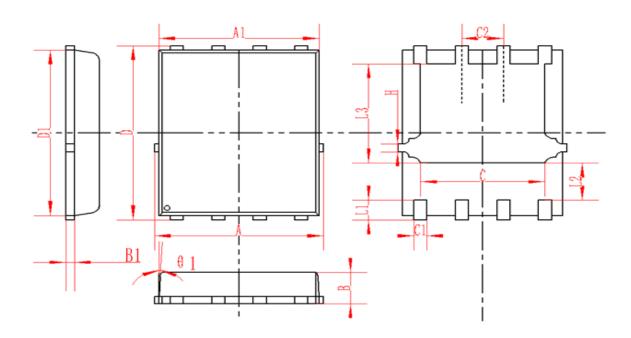


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

DFN5X6-8L Package Information



SYMBOL	MM		INCH			
	MIN	NOM	MAX	MIN	NOM	MAX
Α	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Η	0.24	0.25	0.26	0.009	0.010	0.010



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